ABSTRACT OF THE DISCLOSURE

The present invention provides a semiconductor device including a plurality of wirings or conductive film patterns formed on a semiconductor substrate, and clearances are provided between the wirings or the conductive film patterns. On a corner or an end part of at least one of the wirings or the conductive film patterns, protrusions are formed to protrude, facing the clearances between the wirings or the conductive film patterns. Thereby, defects will not occur in the insulating protective film after an etching step for forming an aperture for exposing a bonding pad, and thus, a semiconductor device is manufactured without being subjected to an additional process that raises the manufacturing cost. The present invention provides also a method of manufacturing the semiconductor device.